

# April 2007

# FFP08H60S Hyperfast 2 Rectifier

## **Features**

- High Speed Switching (t<sub>rr</sub>=45ns(Max.) @ I<sub>F</sub>=8A)
- High Reverse Voltage and High Reliability
- · Avalanche Energy Rated
- Low Forward Voltage( V<sub>F</sub>=2.1V(Max.) @ I<sub>F</sub>=8A )

## **Applications**

- General Purpose
- Switching Mode Power Supply
- · Free-wheeling diode for motor application
- · Power switching circuits

## 8A, 600V Hyperfast 2 Rectifier

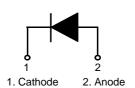
The FFP08H60S is hyperfast2 rectifier ( $t_{rr}$ =45ns(Max.) @  $I_F$ =8A). it has half the recovery time of ultrafast rectifier and is silicon nitride passivated ion-implanted epitaxial planar construction.

This device is intended for use as freewheeling/clamping rectifiers in a variety of switching power supplies and other power switching applications. Its low stored charge and hyperfast soft recovery minimize ringing and electrical noise in many power switching circuits reducing power loss in the switching transistors

## **Pin Assignments**







## Absolute Maximum Ratings T<sub>C</sub> = 25°C unless otherwise noted

Symbol	Parameter	Value	Units
V <sub>RRM</sub>	Peak Repetitive Reverse Voltage	600	V
V <sub>RWM</sub>	Working Peak Reverse Voltage	600	V
$V_R$	DC Blocking Voltage	600	V
I <sub>F(AV)</sub>	Average Rectified Forward Current @ T <sub>C</sub> = 105 °C	8	А
I <sub>FSM</sub>	Non-repetitive Peak Surge Current 60Hz Single Half-Sine Wave	60	А
$T_{J_i}T_{STG}$	Operating Junction and Storage Temperature	- 65 to +150	°C

# Thermal Characteristics $T_C = 25$ °C unless otherwise noted

Symbol	Parameter	Max	Units
$R_{\theta JC}$	Maximum Thermal Resistance, Junction to Case	2.5	°C/W

# **Package Marking and Ordering Information**

<b>Device Marking</b>	Device	Package	Reel Size	Tape Width	Quantity
08H60S	FFP08H60STU	TO-220	=	=	50

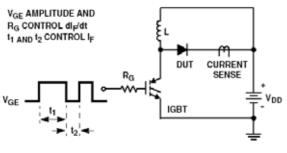
# Electrical Characteristics $T_C = 25^{\circ}C$ unless otherwise noted

Parameter	Conditions		Min.	Тур.	Max	Units
V <sub>FM</sub> <sup>1</sup>	I <sub>F</sub> = 8A I <sub>F</sub> = 8A	T <sub>C</sub> = 25 °C T <sub>C</sub> = 125 °C	-	-	2.1 1.7	V V
I <sub>RM</sub> <sup>1</sup>	$V_{R} = 600V$ $V_{R} = 600V$	$T_{C} = 25  ^{\circ}C$ $T_{C} = 125  ^{\circ}C$	-	-	100 200	μ <b>Α</b> μ <b>Α</b>
t <sub>rr</sub>	$I_F$ =1A, di/dt = 100A/ $\mu$ s, $V_{CC}$ = 30V $I_F$ =8A, di/dt = 100A/ $\mu$ s, $V_{CC}$ = 390V	$T_C = 25 ^{\circ}C$ $T_C = 25 ^{\circ}C$	- -	-	35 45	ns ns
t <sub>a</sub> t <sub>b</sub> Q <sub>rr</sub>	$I_F = 8A$ , di/dt = 100A/ $\mu$ s, $V_{CC} = 390V$	$T_{C} = 25 ^{\circ}\text{C}$ $T_{C} = 25 ^{\circ}\text{C}$ $T_{C} = 25 ^{\circ}\text{C}$	- - -	15 16 18.6	- - -	ns ns nC
W <sub>AVL</sub>	Avalanche Energy (L = 40mH)	•	20	-	-	mJ

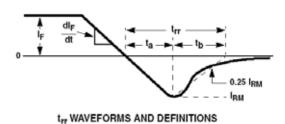
### Notes:

1. Pulse : Test Pulse width =  $300\mu$ s, Duty Cycle = 2%

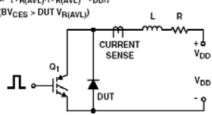
# **Test Circuit and Waveforms**



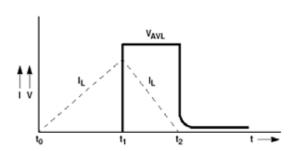
t<sub>rr</sub> TEST CIRCUIT



$$\begin{split} &I_{MAX} = 1A \\ &L = 40mH \\ &R < 0.1\Omega \\ &E_{AVL} = 1/2LI^2 \left[ V_{R(AVL)} / (V_{R(AVL)} - V_{DD}) \right] \\ &Q_1 = IGBT \left( BV_{CES} > DUT \ V_{R(AVL)} \right) \end{split}$$



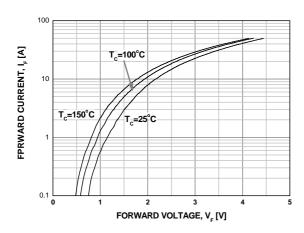
AVALANCHE ENERGY TEST CIRCUIT



AVALANCHE CURRENT AND VOLTAGE WAVEFORMS

# Typical Performance Characteristics T<sub>C</sub> = 25°C unless otherwise noted

Figure 1. Typical Forward Voltage Drop



**Figure 2. Typical Reverse Current** 

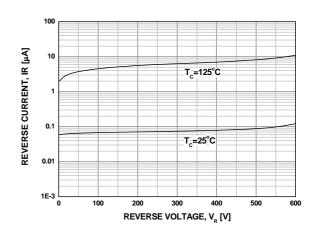


Figure 3. Typical Junction Capacitance

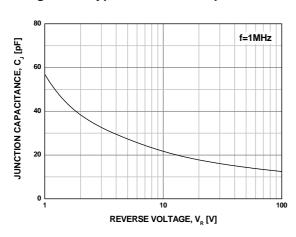


Figure 4. Typical Reverse Recovery Time

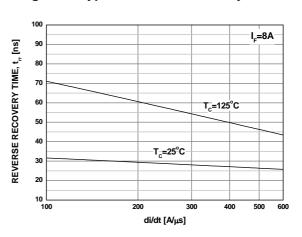


Figure 5. Typical Reverse Recovery Current

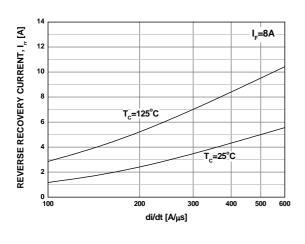
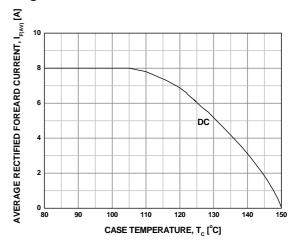


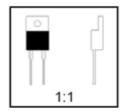
Figure 6. Forward Current Deration Curve



# **Package Demensions**

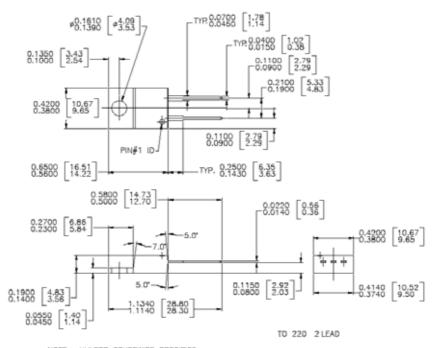
# **TO-220AC**





Scale 1:1 on letter size paper Dimensions shown below are in: inches [millimeters]

Part Weight per unit (gram): 2.24



NOTE : UNLESS OTHERWISE SPECIFIED

1. STANDARD LEAD FINISH : 200 MICROINCHES / 5.08 MICRON MINIMUM LEAD / TIN 15/85 ON OLIN 194 COPPER OR EQUIVALENT

2. DIMENSION BASED ON JEDEC STANDARD TO-220 VARIATION AB, ISSUE J, DATED 3/24/87

Dimensions in Millimeters





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$CROSSVOLT^{TM}$	ISOPLANAR™	QS™	TinyBuck™
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Current Transfer Logic™	MicroPak™	Quiet Series™	TINYOPTO™
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E <sup>2</sup> CMOS <sup>™</sup>	MSX™	RapidConnect™	TinyWire™
EcoSPARK <sup>®</sup>	MSXPro™	ScalarPump™	TruTranslation™
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- A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

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